

## REMARKS/ARGUMENTS

The title of the invention has been amended to "MULTI-CHIP IMAGE SENSOR MODULE" to match with the claimed invention.

5       The specification has been amended without adding new matters and will be explained as below. It is further stated that the substitute specification contains no new matter.

1. Some errors are corrected.

10       2. A resin layer 90 for encapsulating the chip 50 is also provided. The resin layer 90 has been depicted in FIGS 2 and 3 but is not illustrated in the original specification. One of ordinary skill in the art may easily understand that the symbol 90 represents the resin layer 90 for encapsulating the chip 50. Since this feature can be clearly seen on the original drawings, no new matter is added.

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Claims 1-5 are now present in this application. Claims 1-5 have been amended according to the specification without adding new matters.

20       In the amended claim 1, "connected end" has been changed to "connecting end", and the wires for connecting the first connecting ends to the photosensitive chip are defined as "first wires", which are different from the second wires mentioned in claim 3. Also, "the lower surface of the first surface" has been changed to "the lower surface of the first substrate" and "the second ends of the first surface" has been changed to "the second connecting ends of the first substrate". In addition, the "chip" located on the second surface of the second  
25       substrate is defined as a lower chip, which is different from the photosensitive chip.

30       In the amended claims 4 and 5, the "expose resin" has been changed to "resin layer". In the amended claim 5, "the lower chip is a digit" has been changed to "the lower chip is a signal processor", which has been mentioned in page 5, line 12 of the original specification.

**Claim rejections – 35 U.S.C. 112**

The examiner rejects claim 1 under 35 U.S.C. 112.

The first surface of the second substrate in line 19 of claim 1 has been mentioned in the amended claim 1, which recites that the second substrate has the first surface. So, the insufficient antecedent basis has been overcome.

**Claim Objections**

The objections have been overcome in the amended claim 1.

Considerations of the amended claims 1-5 are therefore politely requested.

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In light of the above-mentioned amendments and remarks, Applicant now asserts that all of the grounds for rejection and objection have been traversed or overcome by amendments, and that all of the present claims are in condition for immediate allowance. Applicant therefore requests reconsideration of the objections and rejections, and solicits allowance of the present claims at an early date.

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Thank you for your consideration.

Respectfully submitted,



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**Amendments to the Drawings:**

The attached sheets each labeled "Replacement Sheet" include changes to FIGS. 2-3.

In the amended FIG. 2, a curve around the symbol 80 is erased.

- 5        In the amended FIGS. 2 and 3, the symbol "62" has been changed to "42" because the lead line thereof lead to the photosensitive chip 42. In addition, the symbol "62" and its lead line is added to show the through hole 62 of the lens holder 44. These amendments can be clearly understood from the original drawing, so new matter is added.

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